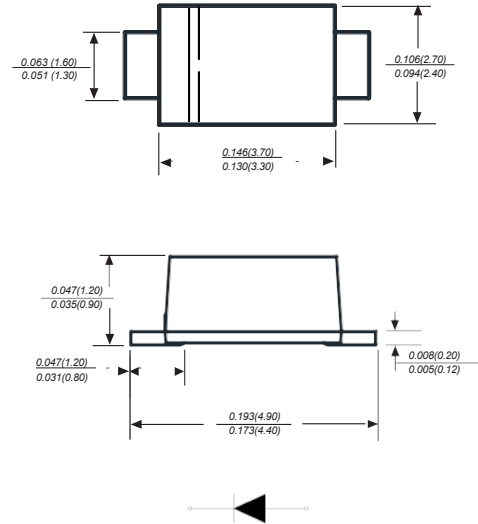


SURFACE MOUNT SCHOTTKY BARRIER DIODES

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0 RoHS-compliant
- ◆ Ideal for printed circuit board
- ◆ Open Junction chip
- ◆ Low reverse leakage High forward surge current
- ◆ capability High temperature soldering guaranteed
- ◆ 250°C/10 seconds at terminals

SMAF



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

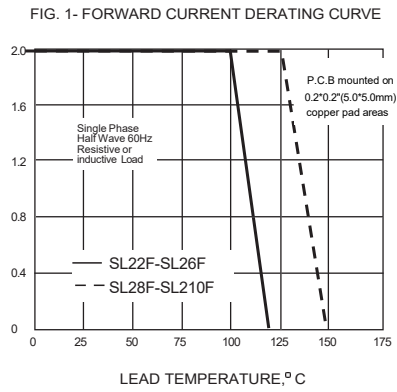
Parameter	SYMBOLS	SL22F	SL24F	SL26F	SL28F	SL210F	UNITS
Marking Code							
Maximum repetitive peak reverse voltage	V _{RRM}	20	40	60	80	100	
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	V
Maximum DC blocking voltage	V _{DC}	20	40	60	80	100	V
Maximum average forward rectified current at TL(see fig.1)	I _(AV)	2.0					A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50					A
Maximum instantaneous forward voltage at 2.0A	V _F	0.45		0.5	0.7		V
Maximum DC reverse current T _A =25℃ at rated DC blocking voltage T _A =125℃	I _R	0.5 10.0			0.2 5.0		mA
Typical junction capacitance (NOTE 1)	C _J	220			180		pF
Typical thermal resistance (NOTE 2)	R _{θJA}	90.0					℃/W
Operating junction temperature range	T _J	-55 to +125			-55 to +150		℃
Storage temperature range	T _{STG}	-55 to +150					℃

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

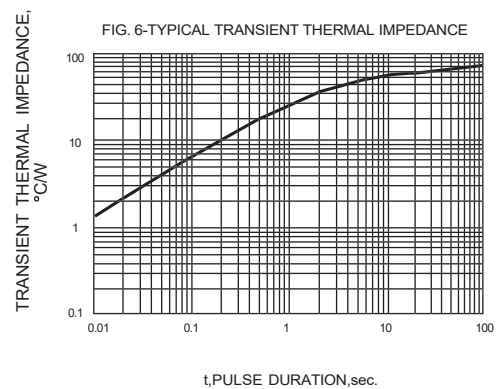
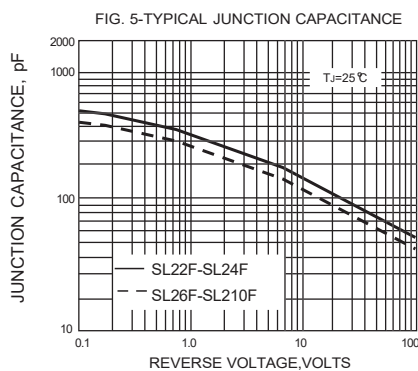
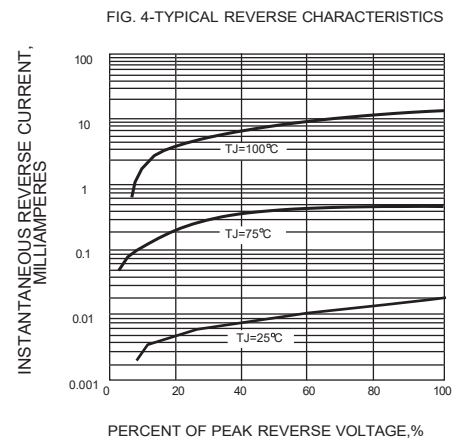
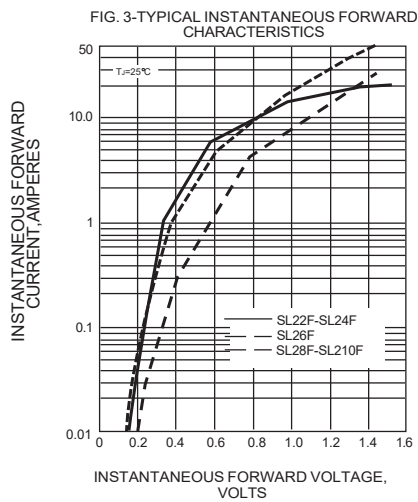
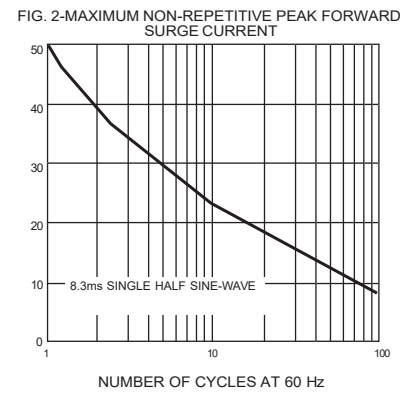
2. P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

Typical Characteristics

AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES



PEAK FORWARD SURGE CURRENT,
AMPERES



The curve above is for reference only.